

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:)	
)	Group Art Unit: 3744
CHEN et al.)	
)	Examiner: CIRIC, L.
Application No: 10/712,708)	
)	Docket No: JLINP174/TLC
Filed: November 12, 2003)	
)	Date: October 24, 2008
For: <u>HEAT DISSIPATION MODULE</u>)	

CERTIFICATE OF E-Filing

I hereby certify that this paper and the documents and/or fees referred to as attached herein are
being electronically filed with the United States Postal Service on **October 24, 2008**.
/Kay Harlow/

AMENDMENT

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This paper is in response to the Official Action mailed on October 8, 2008, and is a second resubmission in response to the Notice of Non-Compliant Amendment, setting a due date of November 8, 2008. Applicant respectfully submits comments in connection with the above-named application.

Amendments to the claims are reflected in the listing of claims which begin on page 2 of this paper.

Remarks/Arguments begin on page 7 of this paper.